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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc620at-04e-ss

4.0 MEMORY ORGANIZATION

4.1 Program Memory Organization

The PIC16C62X has a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 512 x 14 (0000h - 01FFh) for the PIC16C620(A) and PIC16CR620, 1K x 14 (0000h - 03FFh) for the PIC16C621(A) and 2K x 14 (0000h - 07FFh) for the PIC16C622(A) are physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 14 space (PIC16C(R)620(A)) or 1K x 14 space (PIC16C621(A)) or 2K x 14 space (PIC16C622(A)). The RESET vector is at 0000h and the interrupt vector is at 0004h (Figure 4-1, Figure 4-2, Figure 4-3).

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C620/PIC16C620A/ PIC16CR620A

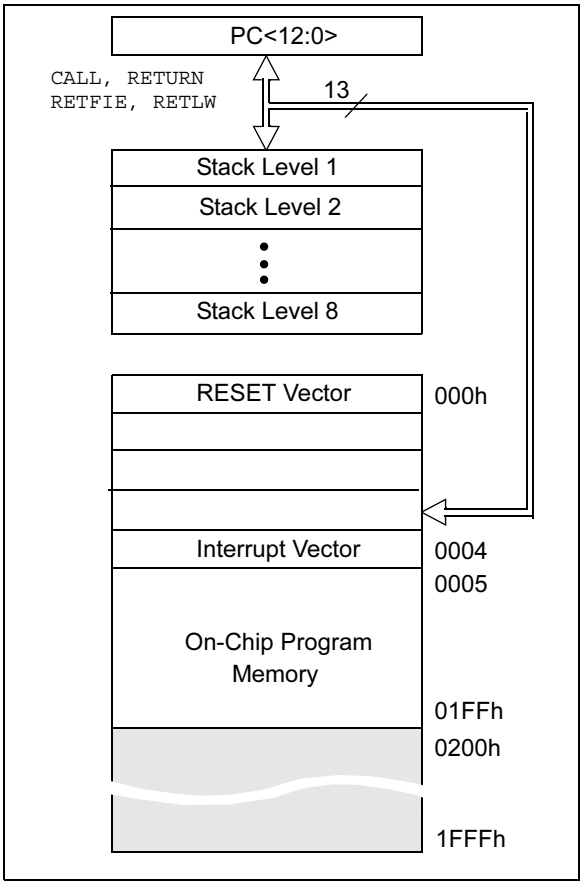


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C621/PIC16C621A

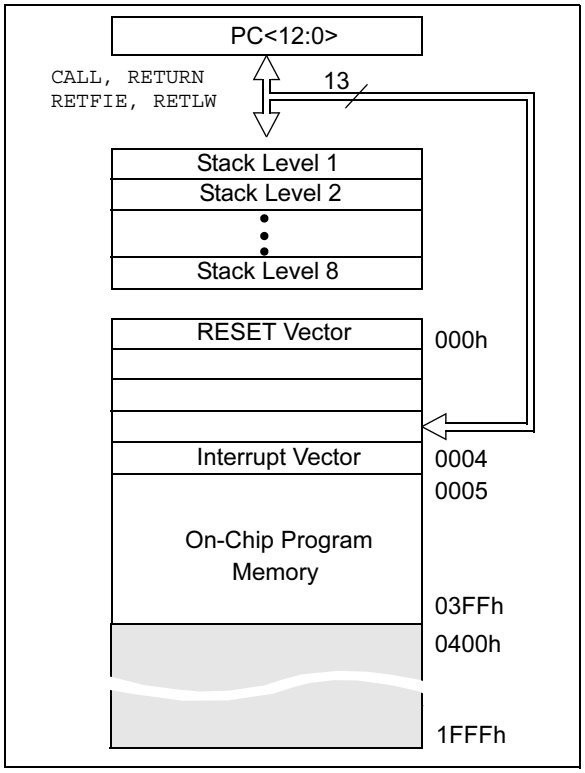
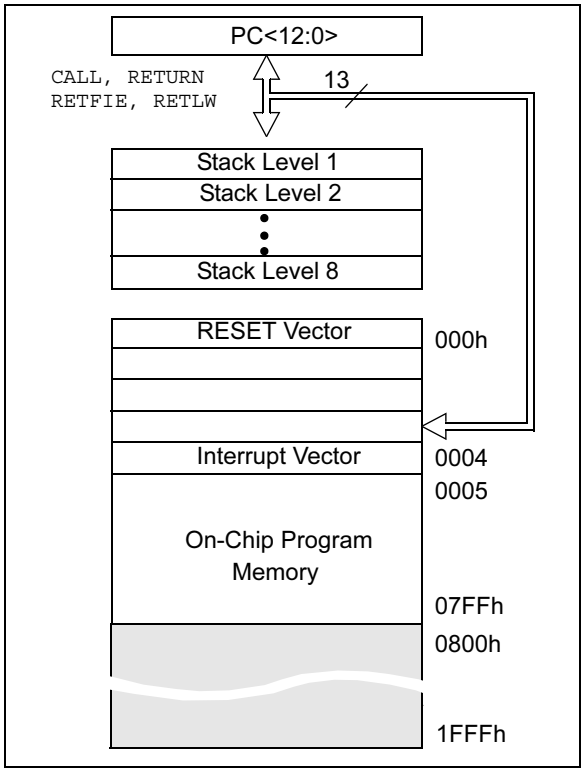


FIGURE 4-3: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C622/PIC16C622A



4.2 Data Memory Organization

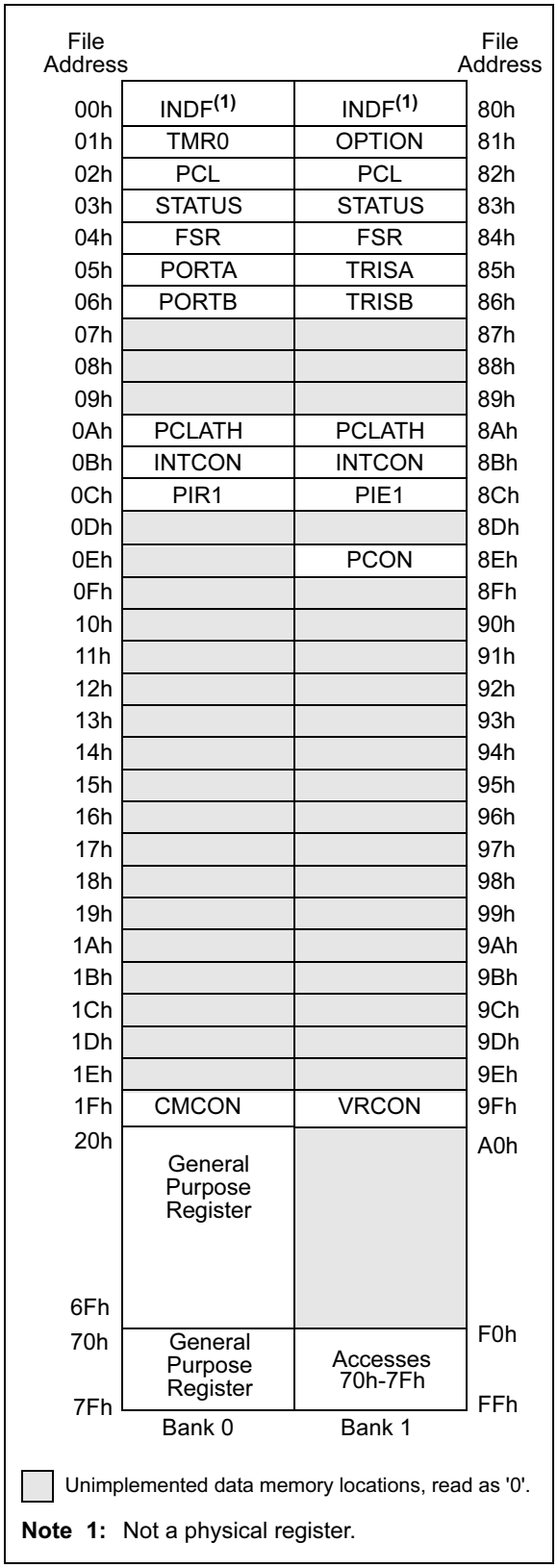
The data memory (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20-7Fh (Bank0) on the PIC16C620A/CR620A/621A and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16C622 and PIC16C622A are General Purpose Registers implemented as static RAM. Some Special Purpose Registers are mapped in Bank 1.

Addresses F0h-FFh of bank1 are implemented as common ram and mapped back to addresses 70h-7Fh in bank0 on the PIC16C620A/621A/622A/CR620A.

4.2.1 GENERAL PURPOSE REGISTER FILE

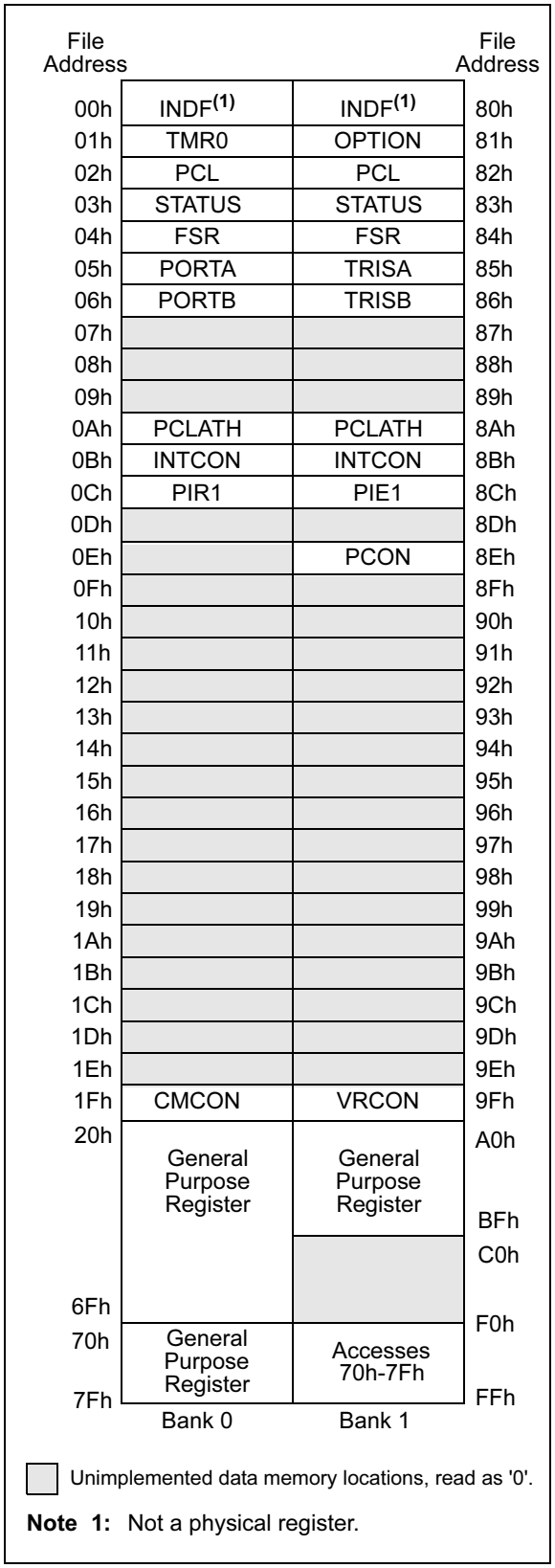
The register file is organized as 80 x 8 in the PIC16C620/621, 96 x 8 in the PIC16C620A/621A/CR620A and 128 x 8 in the PIC16C622(A). Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

FIGURE 4-6: DATA MEMORY MAP FOR THE PIC16C620A/CR620A/621A



Note 1: Not a physical register.

FIGURE 4-7: DATA MEMORY MAP FOR THE PIC16C622A



Note 1: Not a physical register.

4.4 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

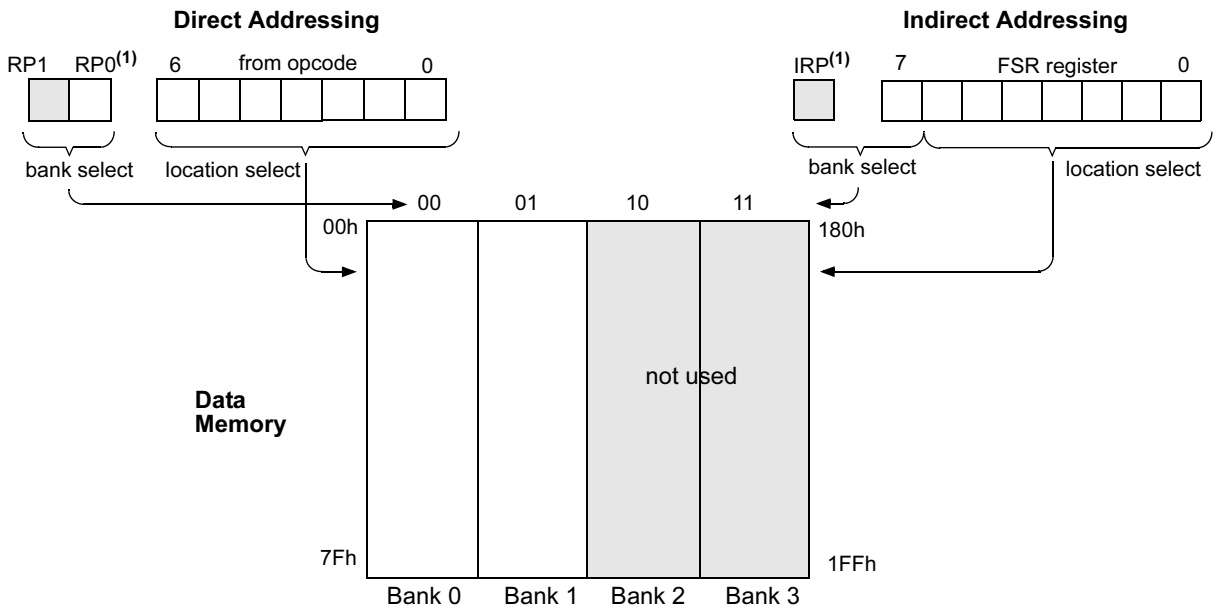
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the File Select Register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-9. However, IRP is not used in the PIC16C62X.

A simple program to clear RAM location 20h-7Fh using indirect addressing is shown in Example 4-1.

EXAMPLE 4-1: INDIRECT ADDRESSING

```
      movlw   0x20       ;initialize pointer
      movwf   FSR        ;to RAM
NEXT  clrf    INDF       ;clear INDF register
      incf    FSR        ;inc pointer
      btfss   FSR,7      ;all done?
      goto    NEXT       ;no clear next
                         ;yes continue
CONTINUE:
```

FIGURE 4-9: DIRECT/INDIRECT ADDRESSING PIC16C62X



For memory map detail see (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7).

Note 1: The RP1 and IRP bits are reserved; always maintain these bits clear.

FIGURE 6-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

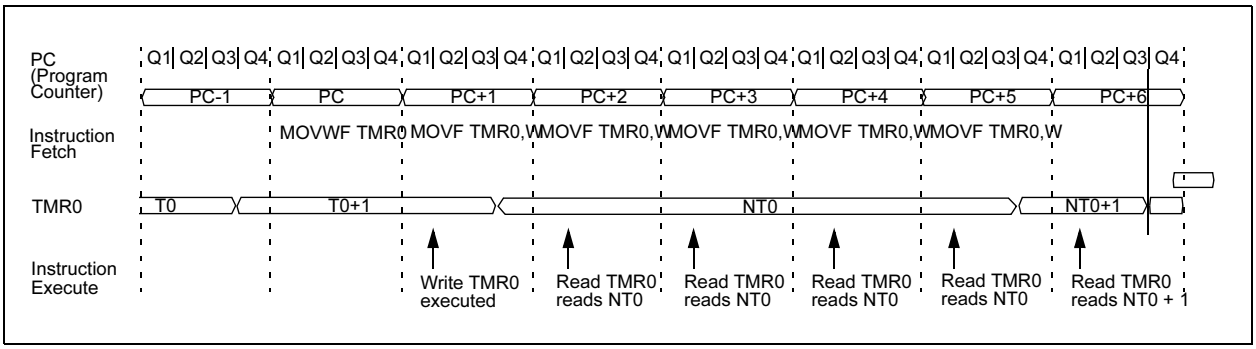
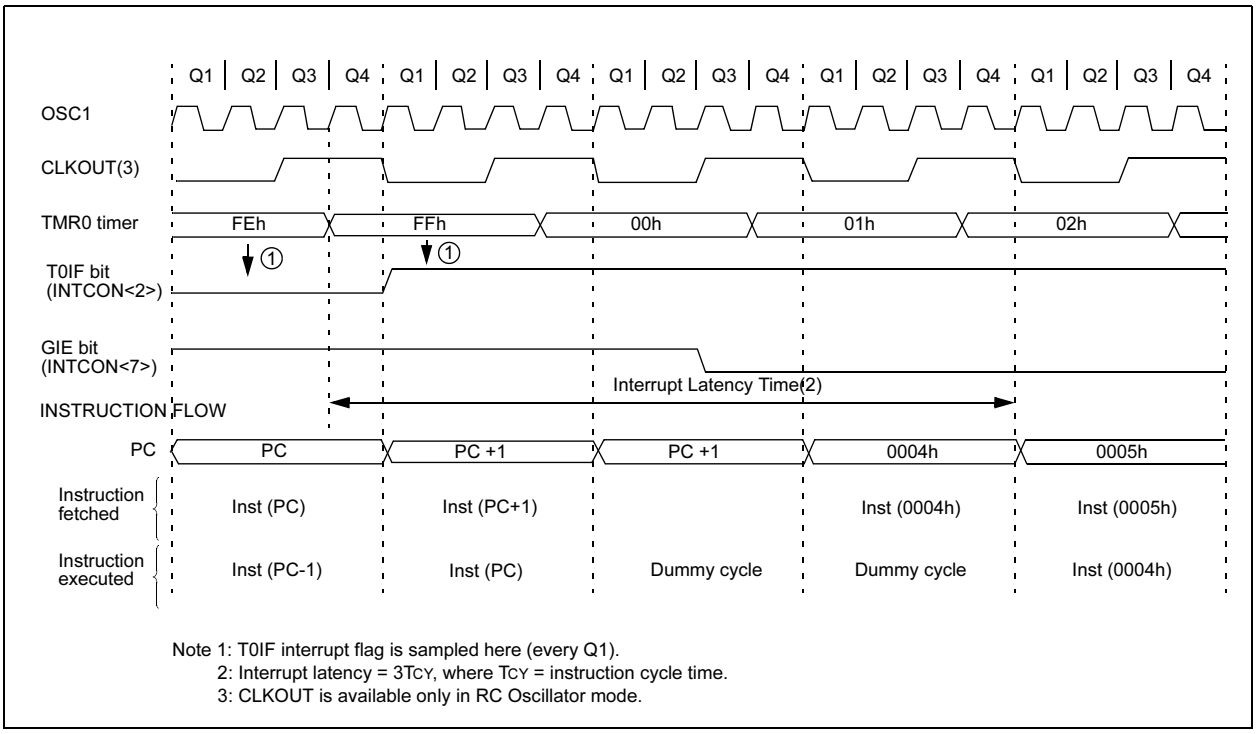


FIGURE 6-4: TIMER0 INTERRUPT TIMING



Note 1: T0IF interrupt flag is sampled here (every Q1).
2: Interrupt latency = 3TCY, where TCY = instruction cycle time.
3: CLKOUT is available only in RC Oscillator mode.

6.2 Using Timer0 with External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

6.2.1 EXTERNAL CLOCK SYNCHRONIZATION

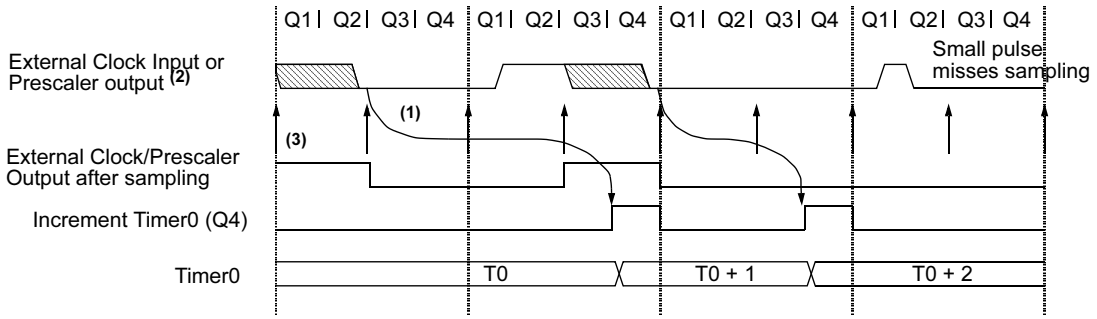
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler, so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

6.2.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the TMR0 is actually incremented. Figure 6-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 6-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ±4Tosc max.
2: External clock if no prescaler selected, Prescaler output otherwise.
3: The arrows indicate the points in time where sampling occurs.

7.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with the RA0 through RA3 pins. The On-Chip Voltage Reference (Section 8.0) can also be an input to the comparators.

The CMCON register, shown in Register 7-1, controls the comparator input and output multiplexers. A block diagram of the comparator is shown in Figure 7-1.

REGISTER 7-1: CMCON REGISTER (ADDRESS 1Fh)

R-0	R-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **C2OUT**: Comparator 2 output
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-

bit 6 **C1OUT**: Comparator 1 output
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-

bit 5-4 **Unimplemented:** Read as '0'

bit 3 **CIS**: Comparator Input Switch
When CM<2:0>: = 001:
1 = C1 VIN- connects to RA3
0 = C1 VIN- connects to RA0
When CM<2:0> = 010:
1 = C1 VIN- connects to RA3
C2 VIN- connects to RA2
0 = C1 VIN- connects to RA0
C2 VIN- connects to RA1

bit 2-0 **CM<2:0>**: Comparator mode.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

7.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit, PIR1<6>, is the comparator interrupt flag. The CMIF bit must be RESET by clearing '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

Note:	If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<6>) interrupt flag may not get set.

The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of CMCON. This will end the mismatch condition.

b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition and allow flag bit CMIF to be cleared.

7.7 Comparator Operation During SLEEP

When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake up the device from SLEEP mode when enabled. While the comparator is powered-up, higher SLEEP currents than shown in the power-down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM<2:0> = 111, before entering SLEEP. If the device wakes up from SLEEP, the contents of the CMCON register are not affected.

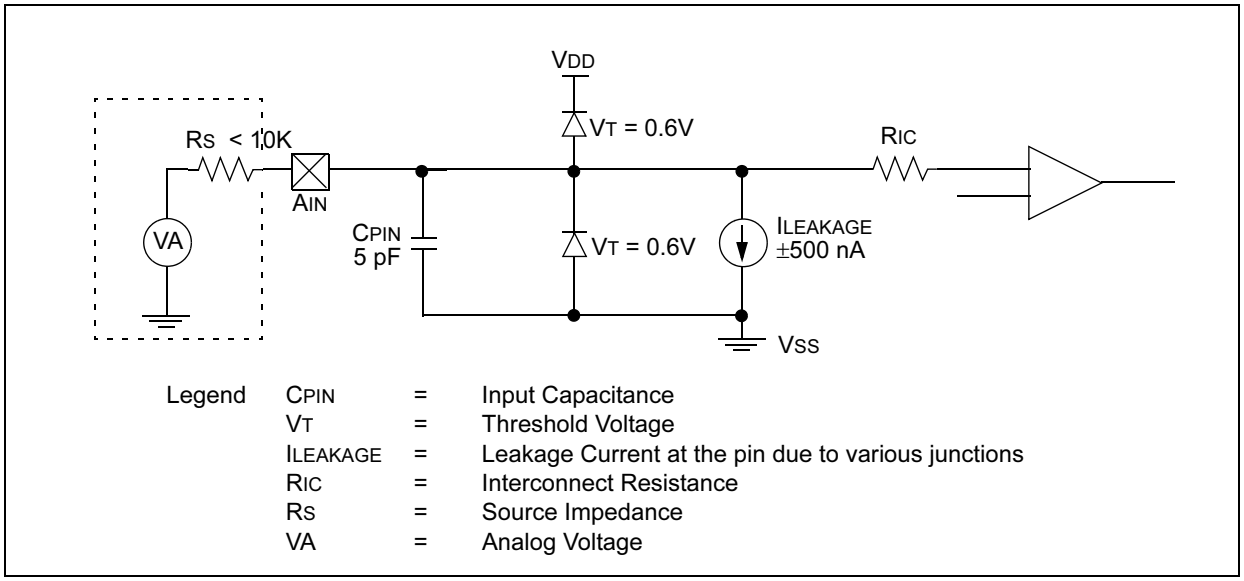
7.8 Effects of a RESET

A device RESET forces the CMCON register to its RESET state. This forces the comparator module to be in the comparator RESET mode, CM<2:0> = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at RESET time. The comparators will be powered-down during the RESET interval.

7.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 7-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to V_{DD} and V_{SS}. The analog input therefore, must be between V_{SS} and V_{DD}. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latchup may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 7-4: ANALOG INPUT MODEL



Legend			
	C_{PIN}	=	Input Capacitance
	V_T	=	Threshold Voltage
	$I_{LEAKAGE}$	=	Leakage Current at the pin due to various junctions
	R_{IC}	=	Interconnect Resistance
	R_S	=	Source Impedance
	VA	=	Analog Voltage

9.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

9.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in RESET until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details.

The POR circuit does not produce an internal RESET when VDD declines.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For additional information, refer to Application Note AN607, “Power-up Trouble Shooting”.

9.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A configuration bit, PWRTE can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Reset is enabled.

The Power-up Time delay will vary from chip-to-chip and due to VDD, temperature and process variation. See DC parameters for details.

9.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-Up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

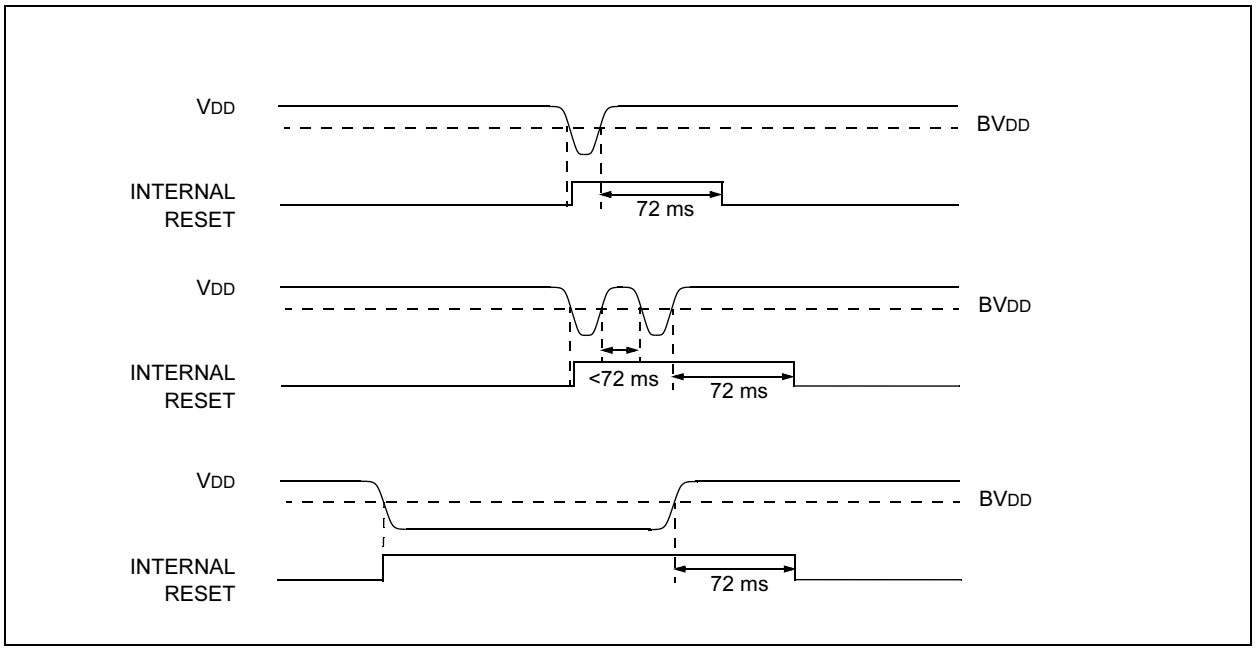
9.4.4 BROWN-OUT RESET (BOR)

The PIC16C62X members have on-chip Brown-out Reset circuitry. A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V refer to VBOR parameter D005 (VBOR) for greater than parameter (TBOR) in Table 12-5. The brown-out situation will RESET the chip. A RESET won’t occur if VDD falls below 4.0V for less than parameter (TBOR).

On any RESET (Power-on, Brown-out, Watchdog, etc.) the chip will remain in RESET until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-Up Timer will execute a 72 ms RESET. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 9-7 shows typical Brown-out situations.

FIGURE 9-7: BROWN-OUT SITUATIONS



9.5 Interrupts

The PIC16C62X has 4 sources of interrupt:

- External interrupt RB0/INT
- TMR0 overflow interrupt
- PORTB change interrupts (pins RB<7:4>)
- Comparator interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. GIE is cleared on RESET.

The "return from interrupt" instruction, `RETFIE`, exits interrupt routine, as well as sets the GIE bit, which re-enable RB0/INT interrupts.

The INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flag is contained in the special register PIR1. The corresponding interrupt enable bit is contained in special registers PIE1.

When an interrupt is responded to, the GIE is cleared to disable any further interrupt, the return address is pushed into the stack and the PC is loaded with 0004h.

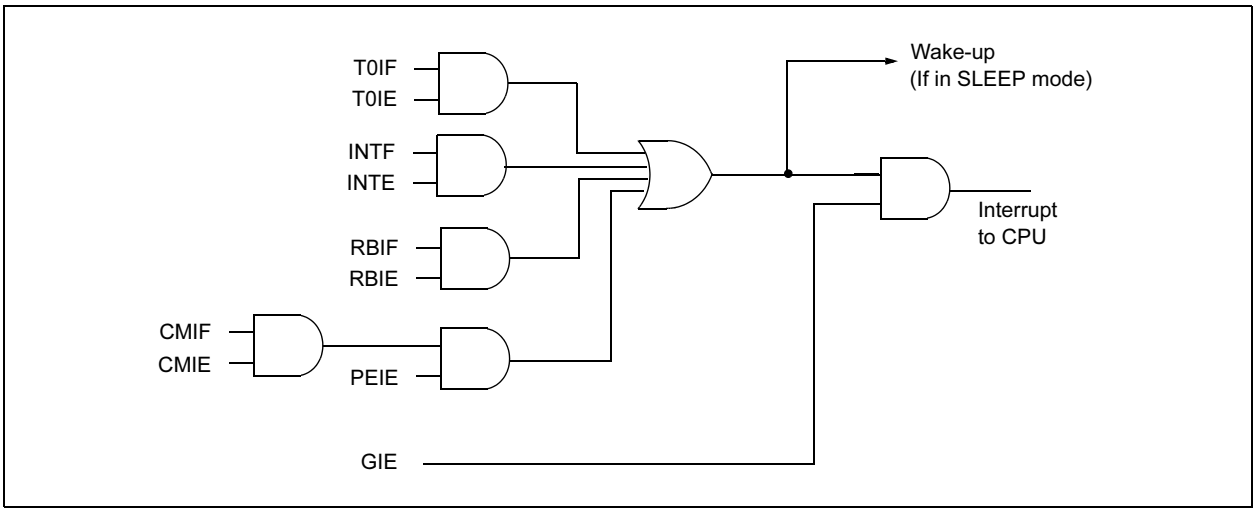
Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid RB0/INT recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 9-16). The latency is the same for one or two cycle instructions. Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests.

Note 1: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

2: When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The CPU will execute a `NOP` in the cycle immediately following the instruction which clears the GIE bit. The interrupts which were ignored are still pending to be serviced when the GIE bit is set again.

FIGURE 9-15: INTERRUPT LOGIC



BCF **Bit Clear f**

Syntax: [*label*] BCF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $0 \rightarrow$ (f<b>)

Status Affected: None

Encoding:

01	00bb	bfff	ffff

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Example
```
BCF     FLAG_REG, 7
```
Before Instruction
FLAG_REG = 0xC7
After Instruction
FLAG_REG = 0x47

BSF **Bit Set f**

Syntax: [*label*] BSF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $1 \rightarrow$ (f<b>)

Status Affected: None

Encoding:

01	01bb	bfff	ffff

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Example
```
BSF     FLAG_REG,   7
```
Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

BTFSC **Bit Test, Skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

01	10bb	bfff	ffff

Description: If bit 'b' in register 'f' is '0', then the next instruction is skipped.
If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded, and a NOP is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example
```
HERE    BTFSC   FLAG,1
FALSE   GOTO    PROCESS_CO
TRUE    •       DE
        •
        •
```
Before Instruction
PC = address HERE
After Instruction
if FLAG<1> = 0,
PC = address TRUE
if FLAG<1>=1,
PC = address FALSE

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Encoding:

00	0001	0000	0011

Description: W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example
```
CLRW
```
Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0100

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. STATUS bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Example
```
CLRWDT
```
Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

COMF **Complement f**

Syntax: [*label*] COMF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: ($\bar{f}$) → (dest)

Status Affected: Z

Encoding:

00	1001	dfff	ffff

Description: The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
COMF    REG1,0
```
Before Instruction
REG1 = 0x13
After Instruction
REG1 = 0x13
W = 0xEC

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: (f) - 1 → (dest)

Status Affected: Z

Encoding:

00	0011	dfff	ffff

Description: Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
DECF    CNT, 1
```
Before Instruction
CNT = 0x01
Z = 0
After Instruction
CNT = 0x00
Z = 1

RETFIE **Return from Interrupt**

Syntax: [*label*] RETFIE

Operands: None

Operation: TOS → PC,
1 → GIE

Status Affected: None

Encoding:

00	0000	0000	1001

Description: Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
RETFIE
```

After Interrupt
PC = TOS
GIE = 1

RETLW **Return with Literal in W**

Syntax: [*label*] RETLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W);
TOS → PC

Status Affected: None

Encoding:

11	01xx	kkkk	kkkk

Description: The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
CALL TABLE;W contains table
        ;offset value
TABLE   •       ;W now has table value
        •
        •
ADDWF PC    ;W = offset
RETLW k1    ;Begin table
RETLW k2    ;
        •
        •
        •
RETLW kn    ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN **Return from Subroutine**

Syntax: [*label*] RETURN

Operands: None

Operation: TOS → PC

Status Affected: None

Encoding:

00	0000	0000	1000

Description: Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
RETURN
```

After Interrupt
PC = TOS

12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62X			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62X			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range is the PIC16C62X range.				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D022	ΔIWDT	WDT Current(5)	—	6.0	20	µA	VDD=4.0V
					25	µA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current(5)	—	350	425	µA	BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	—	100	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current(5)	—	—	300	µA	VDD = 4.0V
D022	ΔIWDT	WDT Current(5)	—	6.0	15	µA	VDD=3.0V
D022A	ΔIBOR	Brown-out Reset Current(5)	—	350	425	µA	BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	—	100	µA	VDD = 3.0V
D023A	ΔIVREF	VREF Current(5)	—	—	300	µA	VDD = 3.0V
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended)

PIC16C62X/C62XA/CR62XA	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
PIC16LC62X/LC62XA/LCR62XA	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended

Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	VIL	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	VSS	—	0.8V 0.15 VDD	V	VDD = 4.5V to 5.5V otherwise
D031		with Schmitt Trigger input	VSS	—	0.2 VDD	V	
D032		$\overline{MCLR}$, RA4/T0CKI,OSC1 (in RC mode)	Vss	—	0.2 VDD	V	**(Note 1)**
D033		OSC1 (in XT and HS)	Vss	—	0.3 VDD	V	
		OSC1 (in LP)	Vss	—	0.6 VDD-1.0	V	
	VIL	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	VSS	—	0.8V 0.15 VDD	V	VDD = 4.5V to 5.5V otherwise
D031		with Schmitt Trigger input	VSS	—	0.2 VDD	V	
D032		$\overline{MCLR}$, RA4/T0CKI,OSC1 (in RC mode)	Vss	—	0.2 VDD	V	**(Note 1)**
D033		OSC1 (in XT and HS)	Vss	—	0.3 VDD	V	
		OSC1 (in LP)	Vss	—	0.6 VDD-1.0	V	
	VIH	Input High Voltage					
		I/O ports					
D040		with TTL buffer	2.0V 0.25 VDD + 0.8V	—	VDD VDD	V	VDD = 4.5V to 5.5V otherwise
D041		with Schmitt Trigger input	0.8 VDD	—	VDD		
D042		$\overline{MCLR}$ RA4/T0CKI	0.8 VDD	—	VDD	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 VDD 0.9 VDD	—	VDD	V	**(Note 1)**

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
PIC16LC62X/LC62XA/LCR62XA	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended

Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	VIH	Input High Voltage					
		I/O ports					
D040		with TTL buffer	2.0V 0.25 VDD + 0.8V	—	VDD VDD	V	VDD = 4.5V to 5.5V otherwise
D041		with Schmitt Trigger input	0.8 VDD	—	VDD		
D042		$\overline{MCLR}$ RA4/T0CKI	0.8 VDD	—	VDD	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 VDD 0.9 VDD	—	VDD	V	**(Note 1)**
D070	IPURB	PORTB weak pull-up current	50	200	400	µA	VDD = 5.0V, VPIN = VSS
D070	IPURB	PORTB weak pull-up current	50	200	400	µA	VDD = 5.0V, VPIN = VSS
	IIL	**Input Leakage Current(2, 3)** I/O ports (Except PORTA)			±1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	—	—	±0.5	µA	Vss ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1, $\overline{MCLR}$	—	—	±5.0	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	IIL	**Input Leakage Current(2, 3)** I/O ports (Except PORTA)			±1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	—	—	±0.5	µA	Vss ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1, $\overline{MCLR}$	—	—	±5.0	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	VOL	Output Low Voltage					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 1.2 mA, VDD = 4.5V, +125°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

FIGURE 12-16: TIMER0 CLOCK TIMING

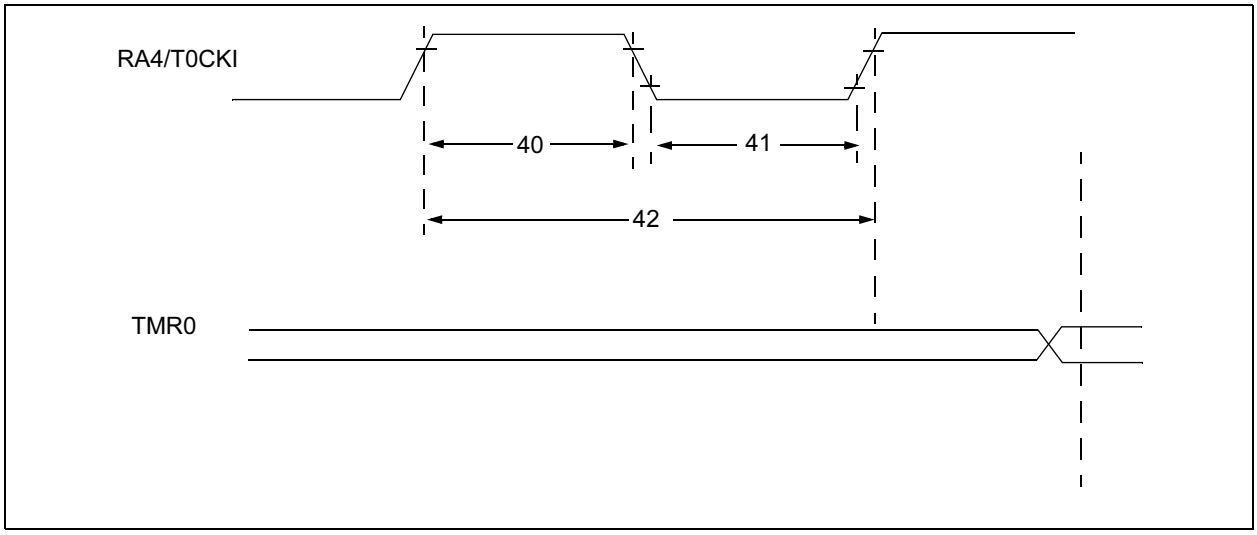


TABLE 12-6: TIMER0 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		TCY + 40* N	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-3: IDD VS. VDD (XT OSC 4 MHZ)

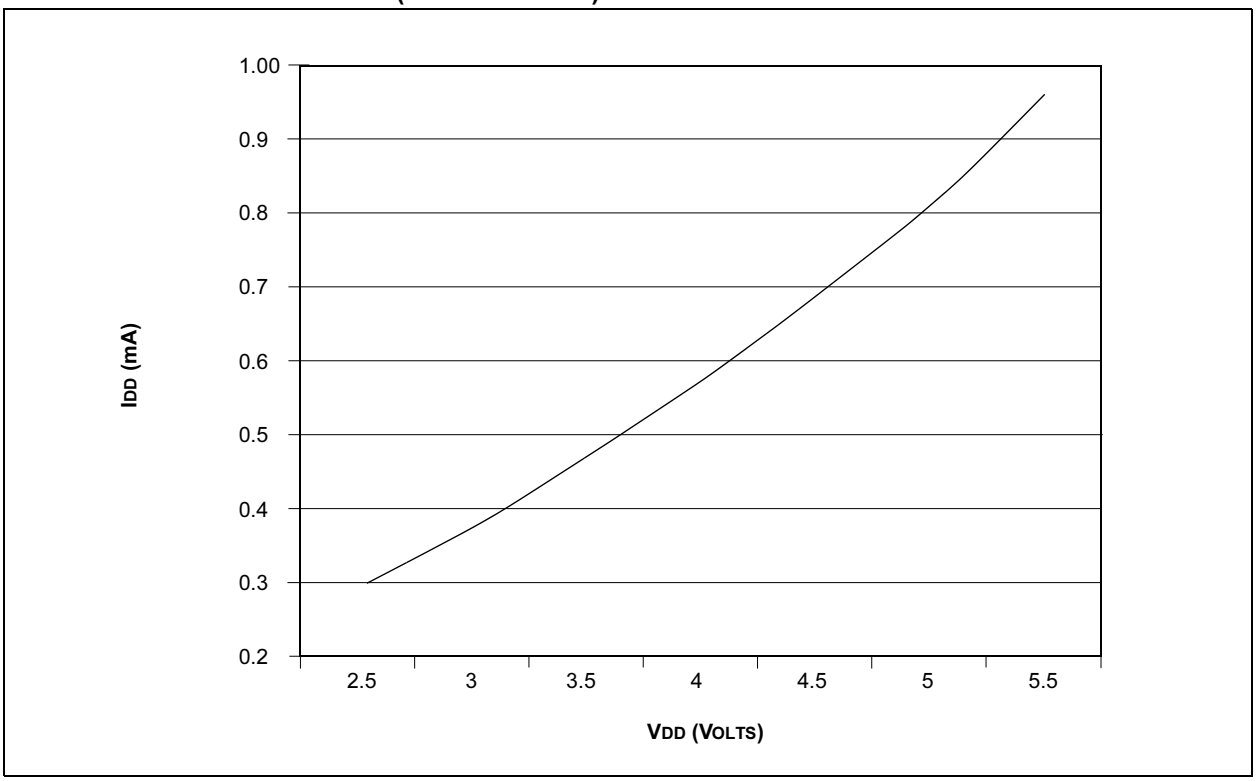
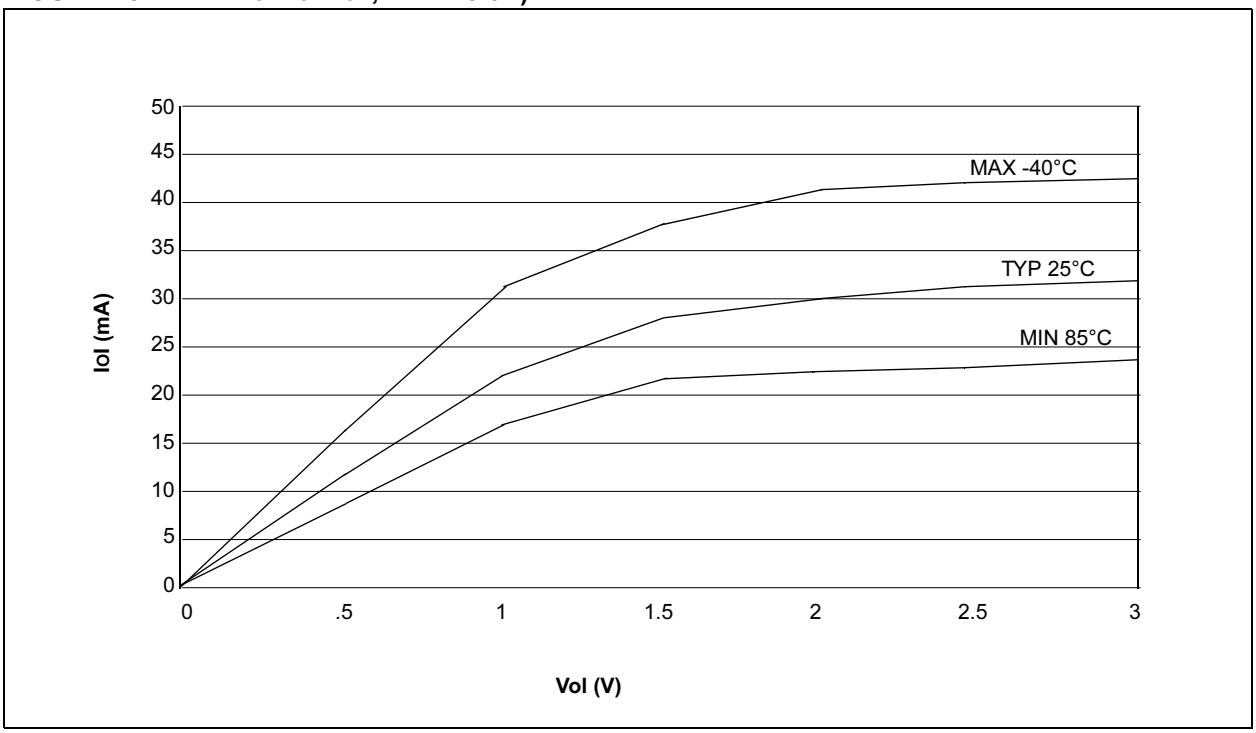
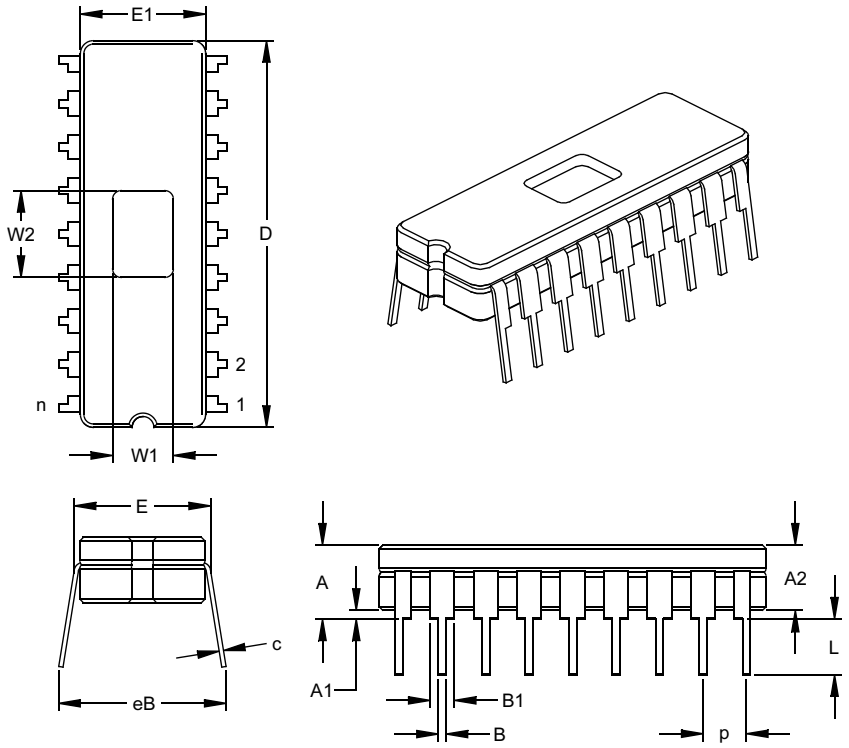


FIGURE 13-4: Iol vs. VOL, VDD = 3.0V)



14.0 PACKAGING INFORMATION

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-036
Drawing No. C04-010

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-XX	X	/XX	XXX
Device	Frequency Range	Temperature Range	Package	Pattern

Device	PIC16C62X: VDD range 3.0V to 6.0V PIC16C62XT: VDD range 3.0V to 6.0V (Tape and Reel) PIC16C62XA: VDD range 3.0V to 5.5V PIC16C62XAT: VDD range 3.0V to 5.5V (Tape and Reel) PIC16LC62X: VDD range 2.5V to 6.0V PIC16LC62XT: VDD range 2.5V to 6.0V (Tape and Reel) PIC16LC62XA: VDD range 2.5V to 5.5V PIC16LC62XAT: VDD range 2.5V to 5.5V (Tape and Reel) PIC16CR620A: VDD range 2.5V to 5.5V PIC16CR620AT: VDD range 2.5V to 5.5V (Tape and Reel) PIC16LCR620A: VDD range 2.0V to 5.5V PIC16LCR620AT: VDD range 2.0V to 5.5V (Tape and Reel)
Frequency Range	04 200 kHz (LP osc) 04 4 MHz (XT and RC osc) 20 20 MHz (HS osc)
Temperature Range	- = 0°C to +70°C I = -40°C to +85°C E = -40°C to +125°C
Package	P = PDIP SO = SOIC (Gull Wing, 300 mil body) SS = SSOP (209 mil) JW* = Windowed CERDIP
Pattern	3-Digit Pattern Code for QTP (blank otherwise)

Examples:

a) PIC16C621A - 04/P 301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301.

b) PIC16LC622- 04I/SO = Industrial temp., SOIC package, 200 kHz, extended VDD limits.

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

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